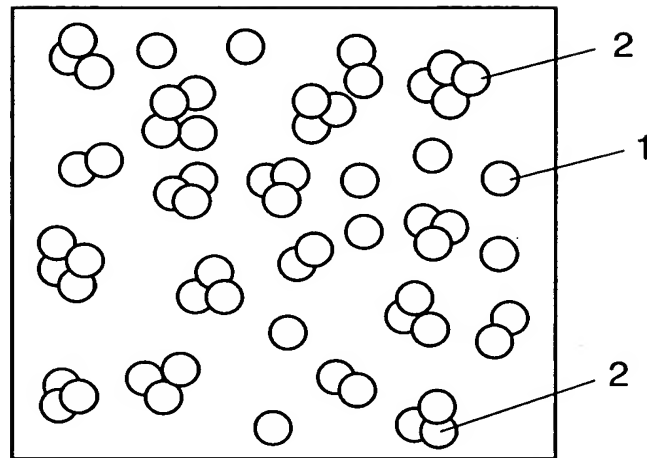


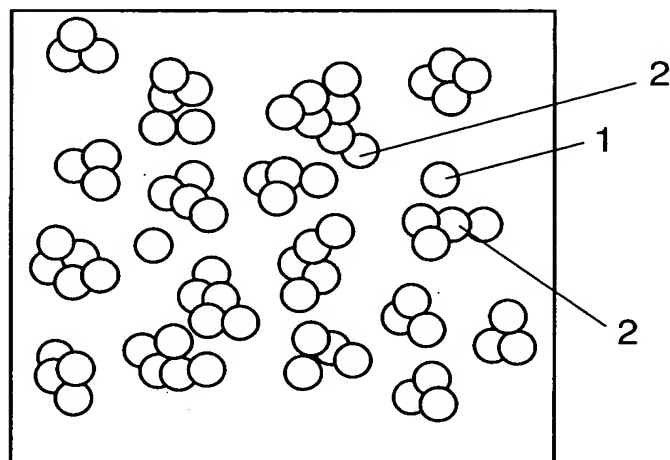
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FIG. 1



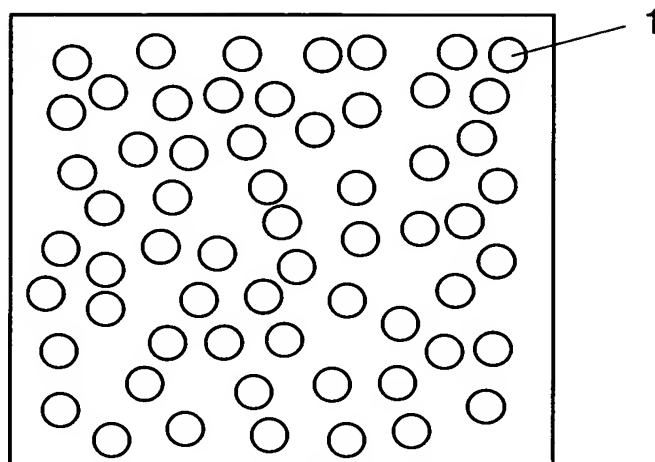
Agglomeration degree 1.60

FIG. 2



Agglomeration degree 3.90

FIG. 3



Agglomeration degree 1.00

FIG. 4A

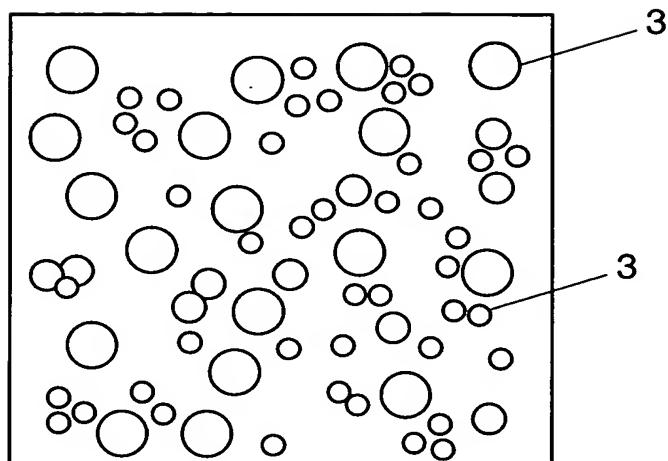


FIG. 4B

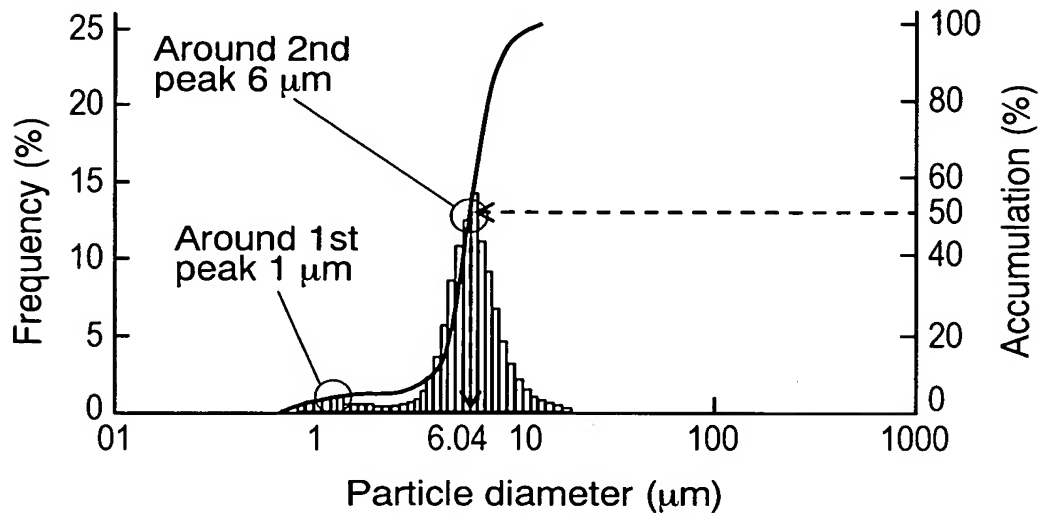
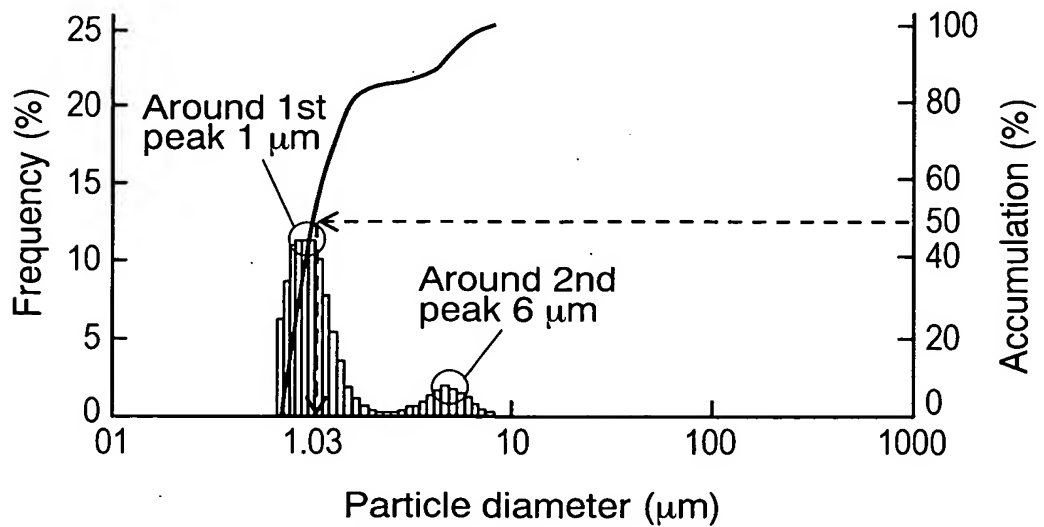
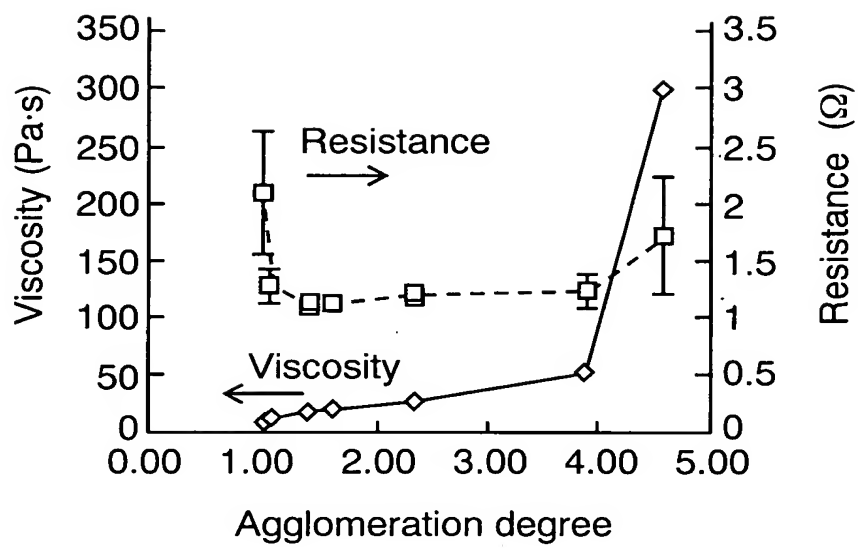
① Volume based particle size distribution ($D_{50}=6.04\mu\text{m}$)② Quantity based particle size distribution ($D_{50}=1.03\mu\text{m}$)

FIG. 5



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FIG. 6A

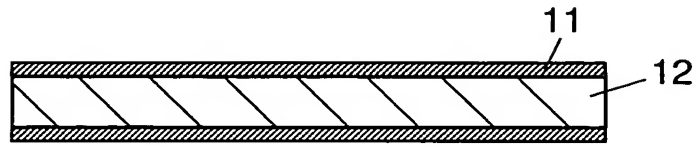


FIG. 6B

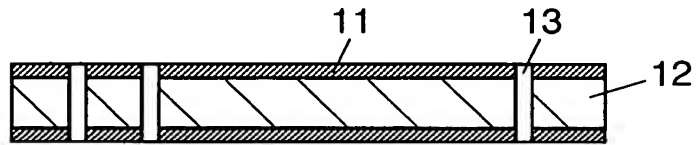


FIG. 6C

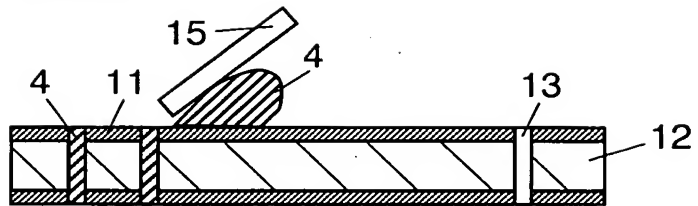


FIG. 6D

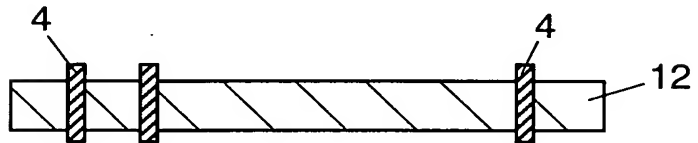


FIG. 6E

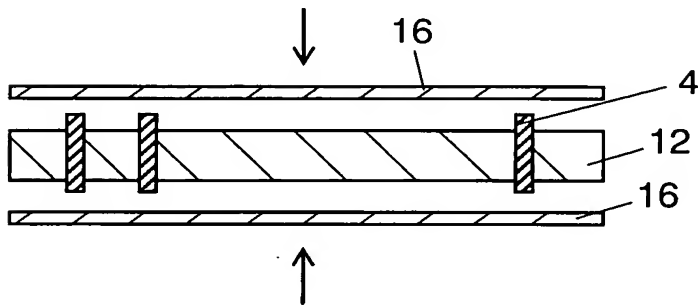


FIG. 6F

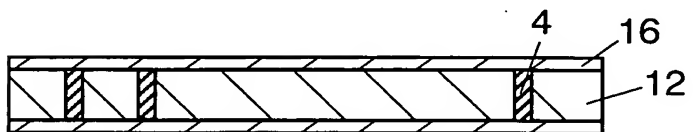
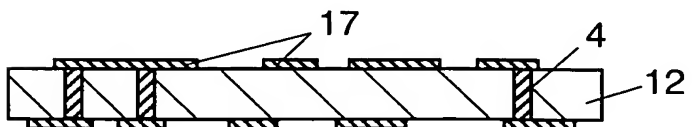


FIG. 6G



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FIG. 7A

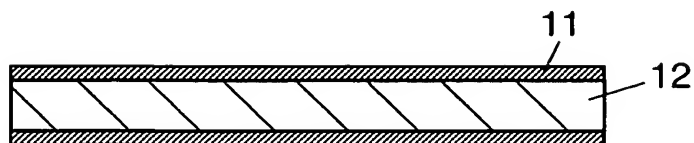


FIG. 7B

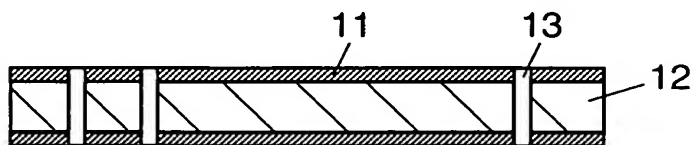


FIG. 7C

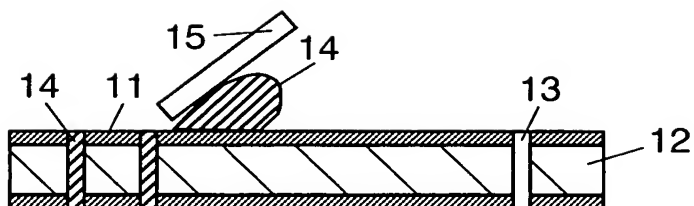


FIG. 7D

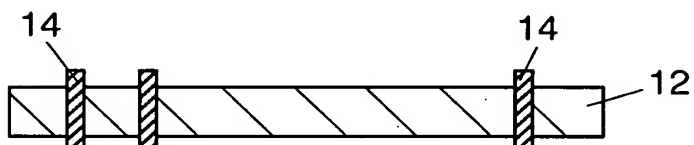


FIG. 7E

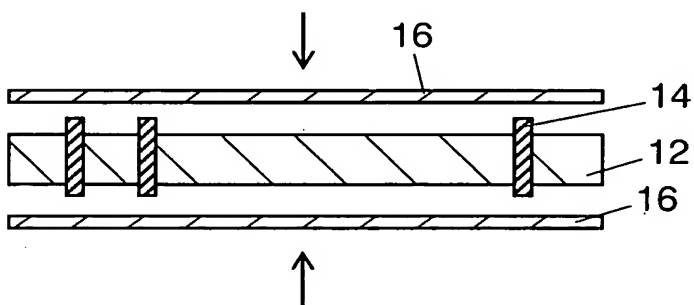


FIG. 7F

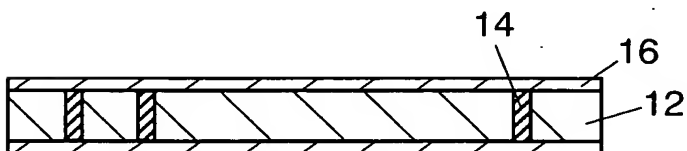


FIG. 7G

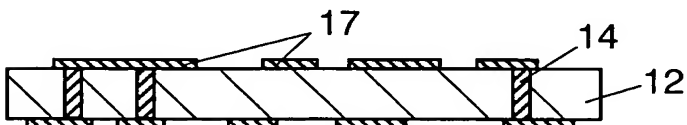
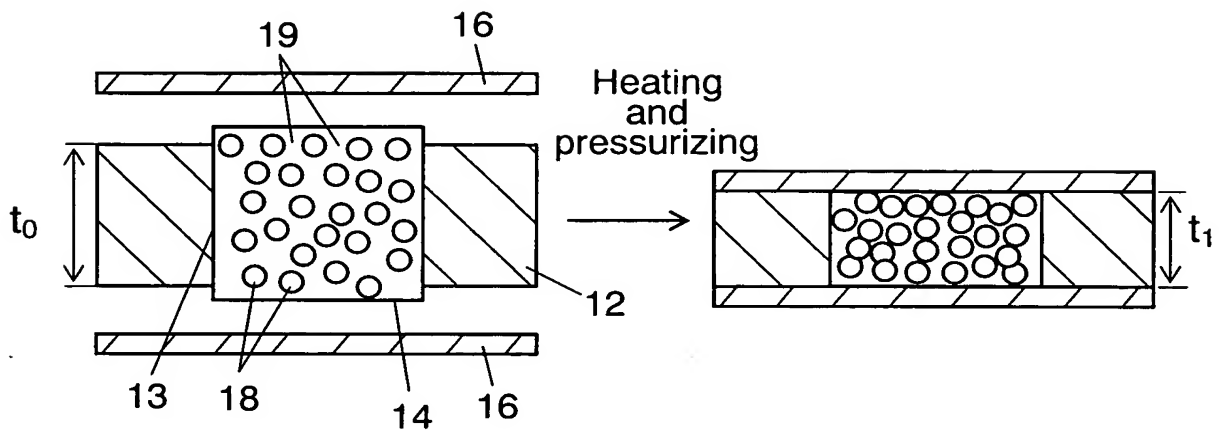


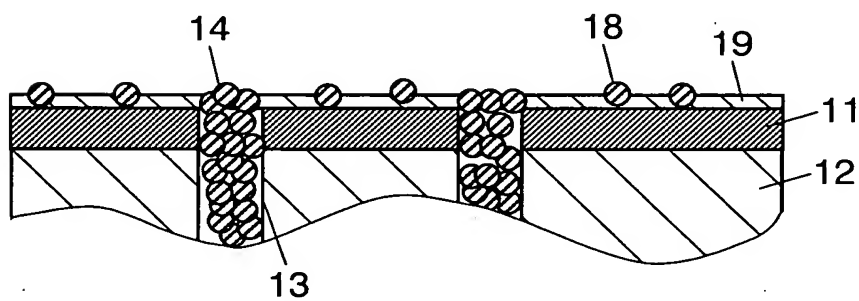
FIG. 8A

FIG. 8B



$$[\text{Substrate compressibility (\%)} = (t_0 - t_1) / t_0 \times 100]$$

FIG. 9



REFERENCE NUMERALS IN THE DRAWINGS

- 1 Primary particle
- 2 Agglomerate
- 3, 18 Conductive particle
- 4.14 Conductive paste
- 11 Releasing film
- 12 Insulating board (prepreg sheet)
- 13 Through-hole
- 15 Squeegee
- 16 Metallic foil
- 17 Wiring pattern
- 19 Binder component